

1    **ABSTRACT OF THE DISCLOSURE**

2            A semiconductor packaging structure mainly has a lead frame with a die  
3    pad and a plurality of leads, a wall portion formed by molding compound  
4    positioned around a periphery of the lead frame, a chip mounted on the die pad and  
5    electrically connected with the plurality of lead via gold wires, and a cover  
6    mounted on the wall portion to enclose the chip. An interval is defined between the  
7    die pad and the plurality of leads for filling with an isolating resin, the interval  
8    further communicates with multiple gaps and each gap is defined between two  
9    adjacent of the plurality of leads, wherein each gap is also filled with the isolating  
10   resin.